



The products are voltage opto-coupl



(Temperature=25°C)

Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
Input	Forward Voltage	V_F	$I_F=10\text{mA}$	-	1.2	1.5	V
	Reverse Current	I_R	$V_R=6\text{V}$	-	-	1	μA
Output	Open Circuit Voltage	V_{OC}	$I_F=10\text{mA}$ $I_O=0\text{mA}$	7	-	-	V
	Short Circuit Current	I_{SC}	$I_F=10\text{mA}$ $V_O=0\text{V}$	5	-	-	μA
Transfer Characteristics	Isolation resistance	R_{IO}	DC500V 40~60%R.H.	10^{12}	-	-	Ω
	Response Time	t_{on}	$I_F=10\text{mA}$	-	100	-	μs
		t_{off}		-	50	-	μs

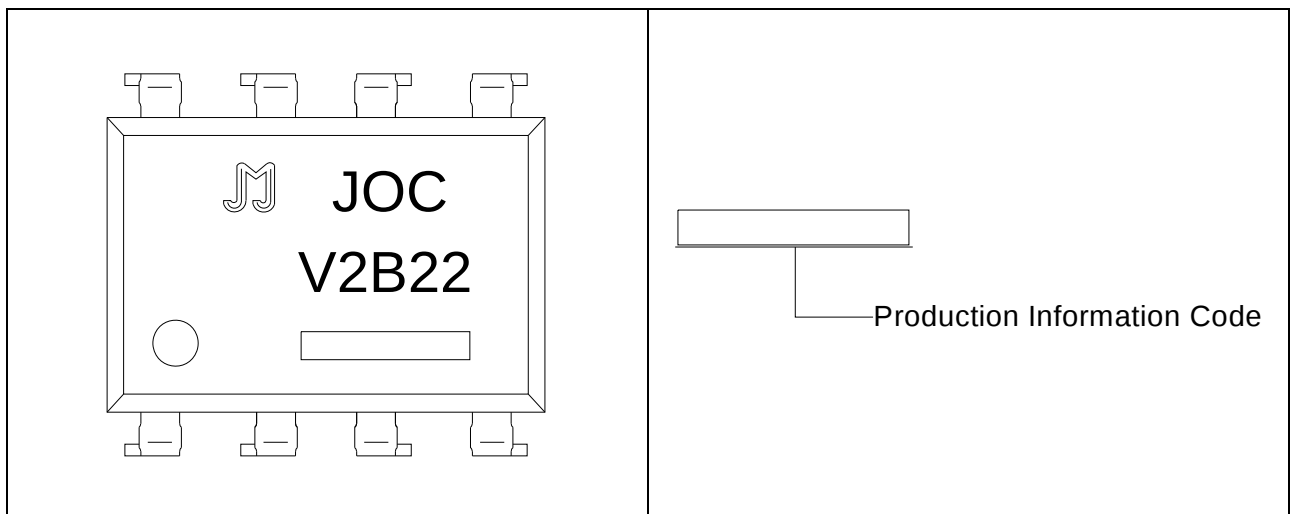


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

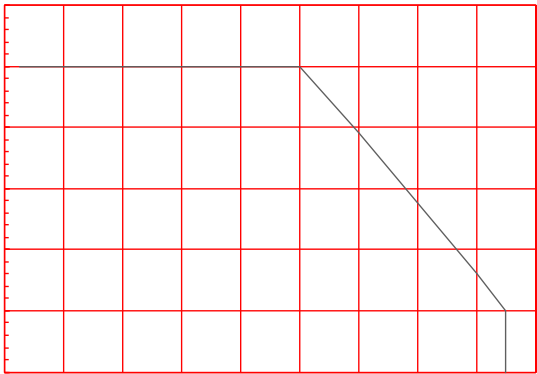


FIG.2: Forward Current vs. Forward Voltage

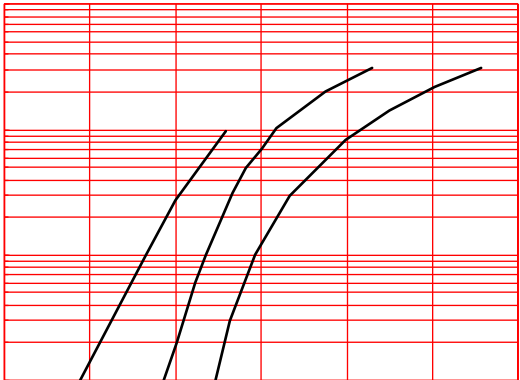


FIG.3: Open Circuit Voltage vs. Forward Current

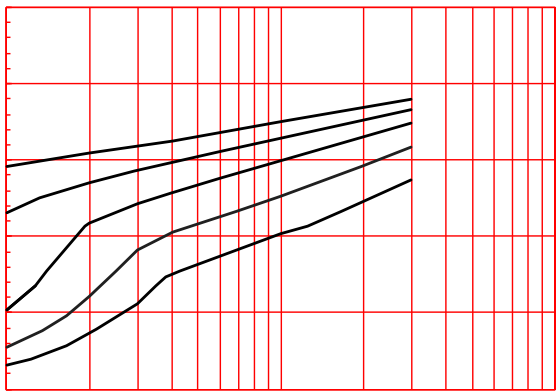
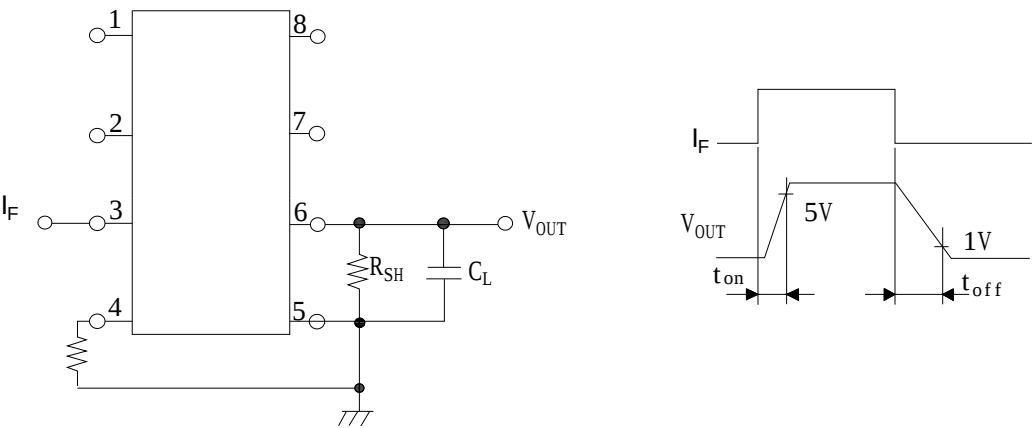
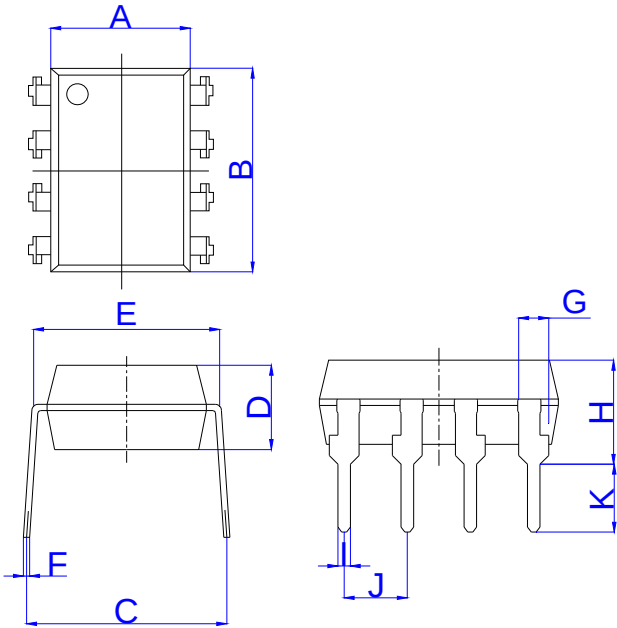


FIG.4: Short Circuit Current vs. Forward Current

FIG.7: Response Time Test Circuit, Waveform

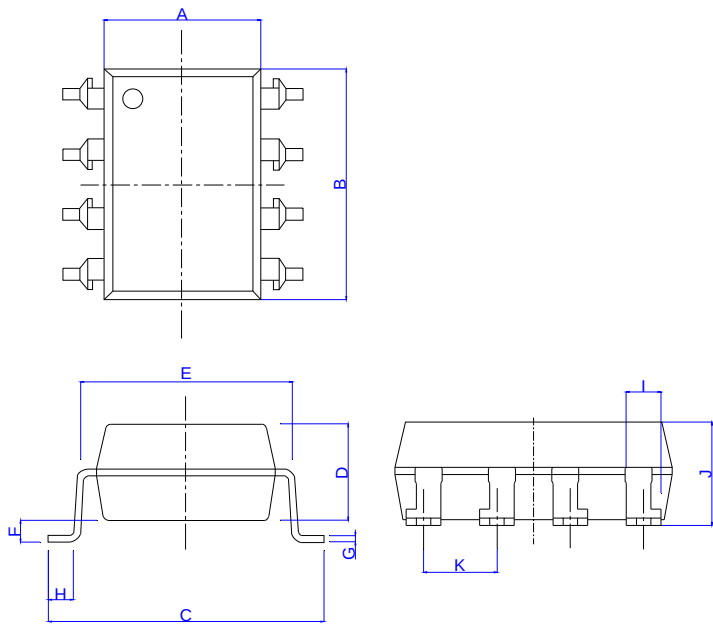


Standard DIP Type:

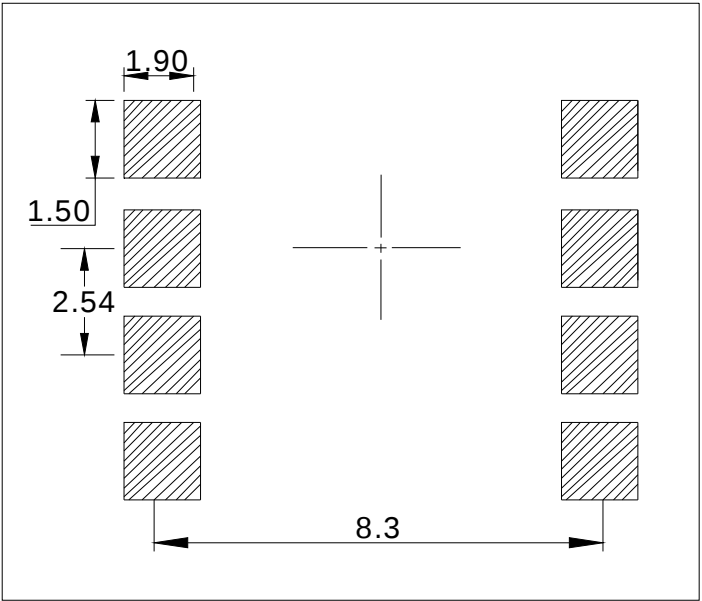


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	7.15		8.95	0.281		0.352
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.15		0.35	0.006		0.014
G	0.90		1.50	0.035		0.059
H	3.90		4.50	0.154		0.177
I	0.40		0.60	0.016		0.024
J	2.29		2.79	0.090		0.110
K	2.24		3.24	0.088		0.128

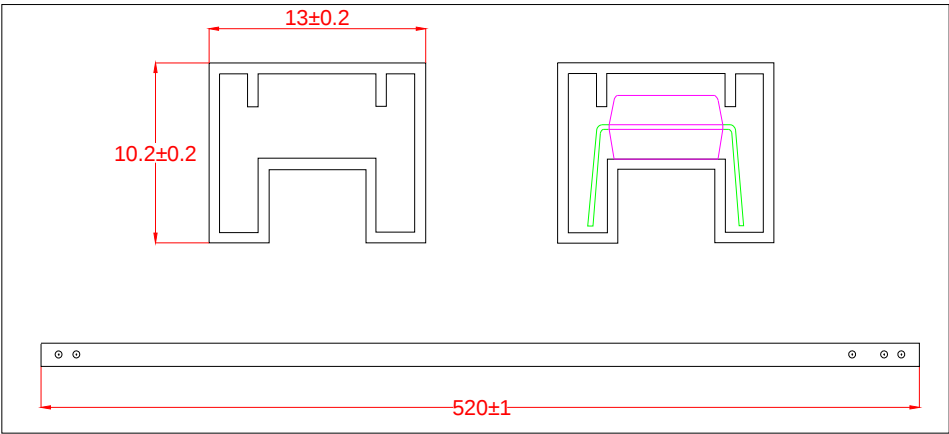
Option SMD Type:



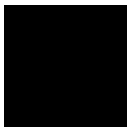
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.20		6.60	0.244		0.260
B	9.40		9.80	0.370		0.386
C	9.50		10.50	0.374		0.413
D	3.20		3.60	0.126		0.142
E	7.32		7.92	0.288		0.312
F	0.05		0.35	0.002		0.014
G	0.16		0.36	0.006		0.014
H	0.60		1.40	0.024		0.055
I	0.90		1.50	0.035		0.059
J	3.30		3.90	0.130		0.154
K	2.29		2.79	0.090		0.110



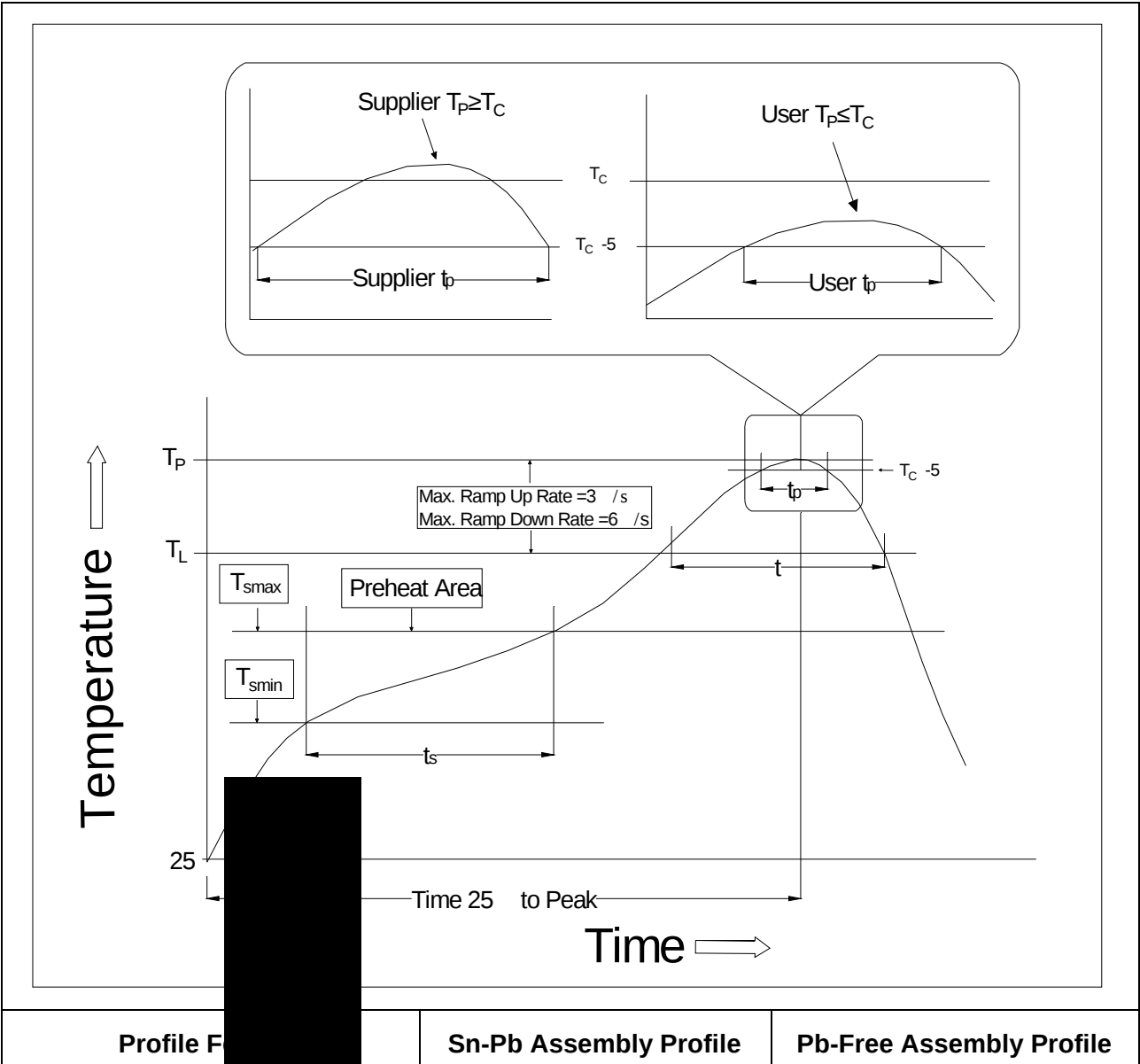
Standard DIP

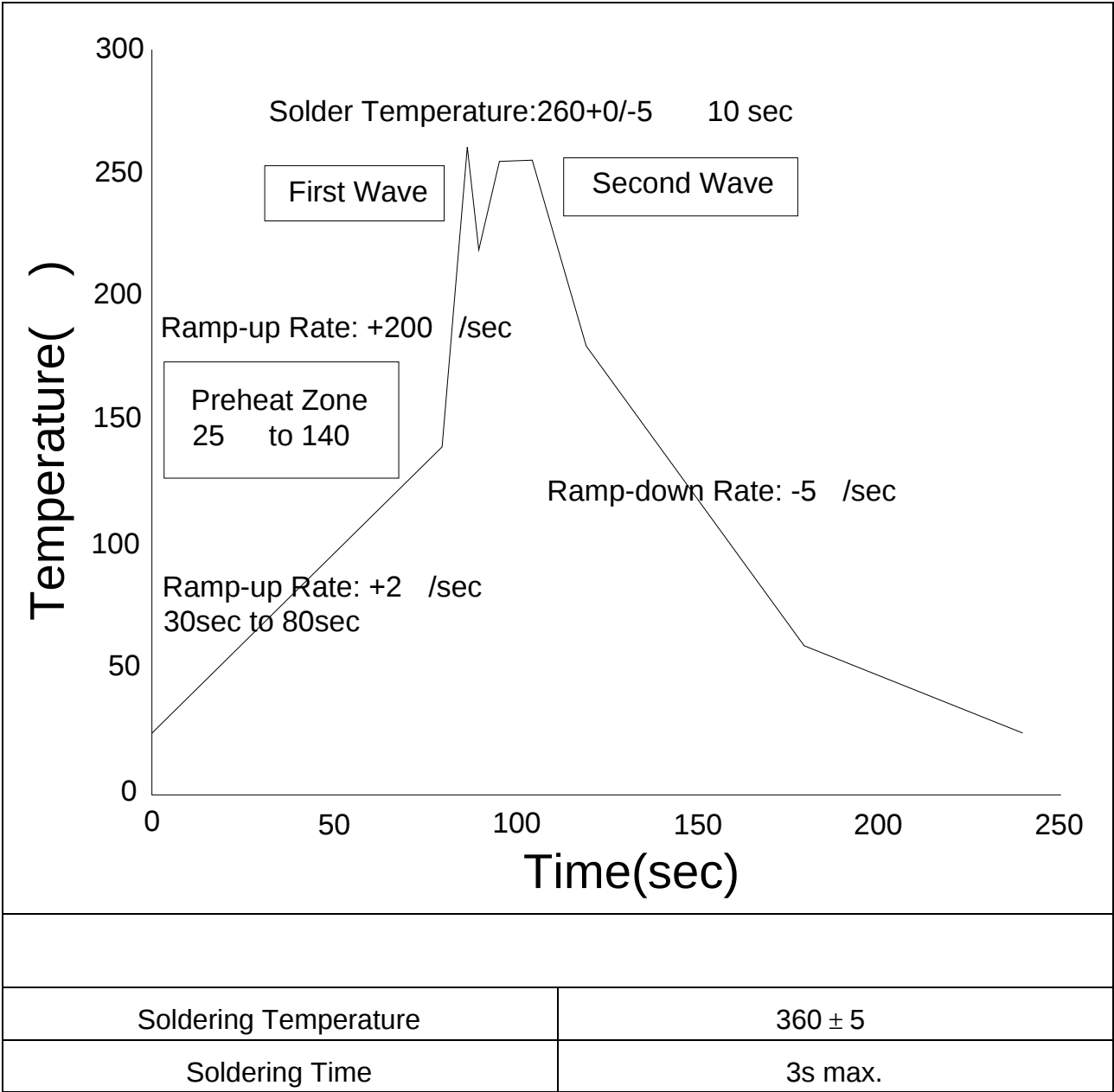


Option S



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.





Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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